



Material Composition Declaration

EPC2034C

Company Name	Efficient Power Conversion (EPC)	Issue Date:	8/9/2019
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0283	Contact Email:	yanping.ma@epc-co.com
Part Weight:	18.6 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	13.9274	74.7441	77.7290	747441
	Silicon oxide	7631-86-9	0.0746	0.4004		4004
	Silicon nitride	12033-89-5	0.0272	0.1459		1459
	Gallium nitride	25617-97-4	0.1164	0.6247		6247
	Aluminum	7429-90-5	0.1431	0.7680		7680
	Aluminum nitride	24304-00-5	0.0315	0.1691		1691
	Titanium	7440-32-6	0.0029	0.0154		154
	Titanium nitride	25583-20-4	0.0122	0.0657		657
	Copper	7440-50-8	0.0048	0.0256		256
	Tungsten	7440-33-7	0.0032	0.0170		170
	Polyimide		0.1403	0.7531		7531
Under Bump Metal	Titanium	7440-32-6	0.0017	0.0091	0.7694	91
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.1417	0.7603		7603
Solder Bump	Tin	7440-31-5	3.8262	20.5341	21.5017	205341
	Silver	7440-22-4	0.1603	0.8601		8601
	Copper	7440-50-8	0.0200	0.1075		1075
Sum in total:			18.6335	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.